

Quarterly Reliability Monitoring Results

Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number PTVS14VS1UR-Q Part Description											
									Nexperia DHAM	Protection			
									SMD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects							
			TEST										
			Pre- and Post-Stress										
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below							
		JESD22-A113	24 5										
	PC	Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85%	24 hours 168 hours										
# A1	Preconditioning	Reflow soldering	3 cycles	438	24630	0							
# A1		MIL-STD-750-1	,	430	24030	0							
	HTRB	M1038 Method A											
		Tj = Tjmax, Vr = 100% of max. datasheet											
# B1	Bias	reverse voltage	1000 hours	166	10040	0							
	тс	JESD22-A104											
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	131	7760	0							
# A3 or	UHAST Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %											
# A3 or	Olibiased HAST	· · · · · · · · · · · · · · · · · · ·	- 96 hours	131	7760	0							
	AC	JESD22-A102 Tamb = 121 °C, RH = 100 %											
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)											
# AJ alt	, rate et a l'est et a	1.055a.c 255 iv a (2517 pola)											
	H3TRB	JESD22-A101											
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of											
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^[1]	1000 hours	131	7760	0							
		MIL-STD-750 Method 1037											
	IOL	ton = toff, devices powered to insure ΔTj =											
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.							
	no	150000 4444											
" 60	RSH Resistance to Solder Heat	JESD22-A111		45	1250	•							
# C8		200 -C = 5 -C	10 s	45	1350	0							
# C10	SD Solderability	J-STD-002		111	1110	0							
# CIU	Solderability	J J1D 002		111	1110	U							

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Protection	10040	0	0,42	2,36E+09

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